

General Description

The MY3035Q is the single P-Channel logic enhancement mode power field effect transistors to provide excellent $R_{DS(on)}$, low gate charge and low gate resistance.

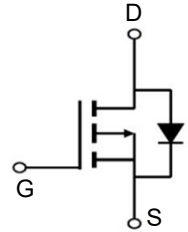
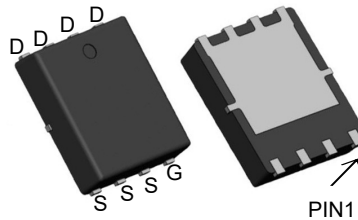


Features

V_{DSS}	-30	V
I_D	-35	A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	< 9	m Ω
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	< 13	m Ω

Application

- Battery protection
- Load switch
- Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY3035Q	PDFN3*3-8L	MY3035Q	5000

Absolute Maximum Ratings ($T_J=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current—Continuous ^a	I_D	-35	A
		-22	
Drain Current –Pulsed ^a	I_{DM}	-120	A
Power Dissipation ($T_C=25^{\circ}C$)	P_D	21	W
Power Dissipation – Derate above $25^{\circ}C$		0.17	
Storage Temperature Range	T_{STG}	-55 ~ +150	$^{\circ}C$
Operating Junction Temperature Range	T_J	-55 ~ +150	$^{\circ}C$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^{\circ}C/W$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	6	$^{\circ}C/W$

Electrical Characteristics ($T_A=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-30	---	---	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=-30V, V_{GS}=0V, T_J=25^{\circ}C$	---	---	-1	μA
		$V_{DS}=-24V, V_{GS}=0V, T_J=100^{\circ}C$	---	---	-10	μA
Gate-Body Leakage	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA

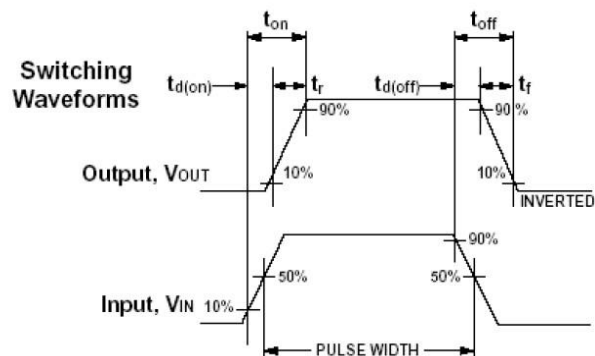
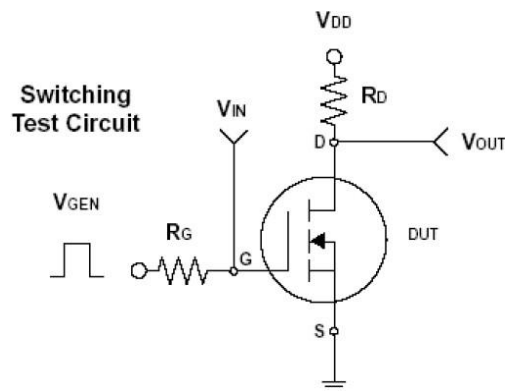
On Characteristics ^a						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.3	---	-1.8	V
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =-10V, I _D =-15A	---	7	9	mΩ
		V _{GS} =-4.5V, I _D =-9A	---	10	13	
Forward Transconductance	g _{fs}	V _{DS} =-10V, I _D =-12A	---	10.5	---	S
Drain-Source Diode Characteristics ^a						
Continuous Source Current	I _S	V _G =V _D =0V, Force Current	---	---	-30	A
Pulsed Source Current	I _{SM}		---	---	-120	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-1.0A, T _J =25℃	---	---	-1.0	V
Dynamic Characteristics ^b						
Input Capacitance	C _{iss}	V _{DS} =-15V, V _{GS} =0V, F=1MHz	---	1530	2210	pF
Output Capacitance	C _{oss}		---	160	240	
Reverse Transfer Capacitance	C _{rss}		---	105	160	
Switching Characteristics ^b						
Total Gate Charge	Q _g	V _{DS} =-15V, V _{GS} =-4.5V, I _D =-12A	---	14.6	21	nC
Gate-Source Charge	Q _{gs}		---	4.1	6	
Gate-Drain Charge	Q _{gd}		---	6.3	9	
Turn-On Delay Time	T _{d(on)}	V _{DD} =-15V, V _{GS} =-10V, R _G =6Ω I _D =-1A	---	9	17	ns
Rise Time	T _r		---	21.8	41	
Turn-Off Delay Time	T _{d(off)}		---	59.8	114	
Fall Time	T _f		---	14.4	27	

Notes: a. Repetitive Rating: Pulsed width limited by maximum junction temperature.

b. Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

c. Guaranteed by design, not subject to production testing.

Switching Time Test Circuit and Waveforms



Soldering Methods For Products

1. Storage environment : Temperature=10°C~35°C, Humidity=65%±15%
2. Reflow soldering of surface mount devices

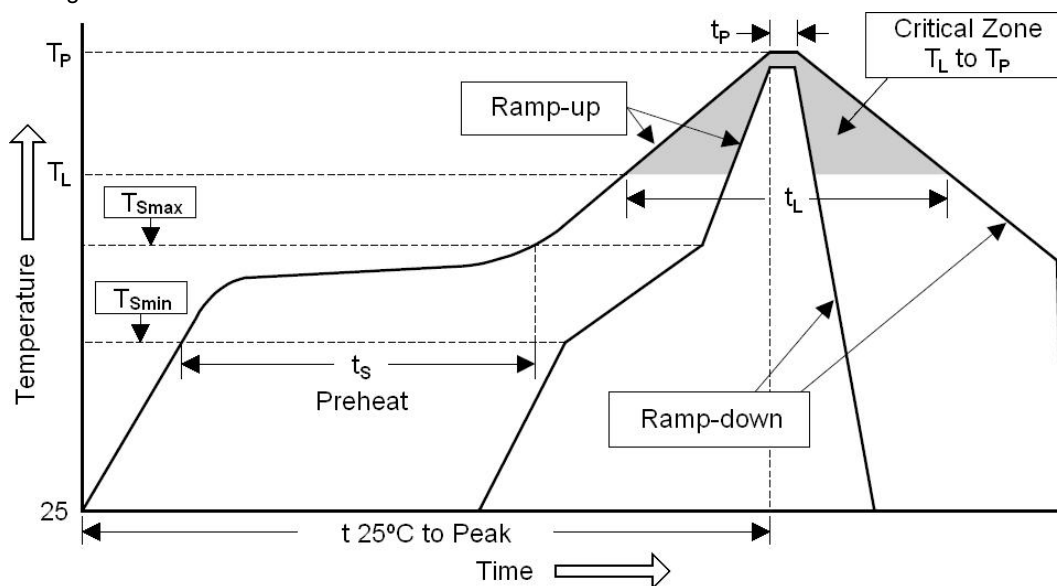


Figure : Temperature Profile

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	< 3°C/sec	< 3°C/sec
Preheat - Temperature Min (T_{Smin}) - Temperature Max (T_{Smax}) - Time (Min to Max) (t_s)	100°C 150°C 60 ~ 120 sec	100°C 200°C 60 ~ 180 sec
T_{Smax} to T_L - Ramp-up rate	< 3°C/sec	< 3°C/sec
Time maintained above: - Temperature (T_L) - Time (t_L)	183°C 60 ~ 150 sec	217°C 60 ~ 150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_P)	10 ~ 30 sec	20 ~ 40 sec
Ramp-down rate	< 6°C/sec	< 6°C/sec
Time 25°C to Peak Temperature	< 6 minutes	< 8 minutes

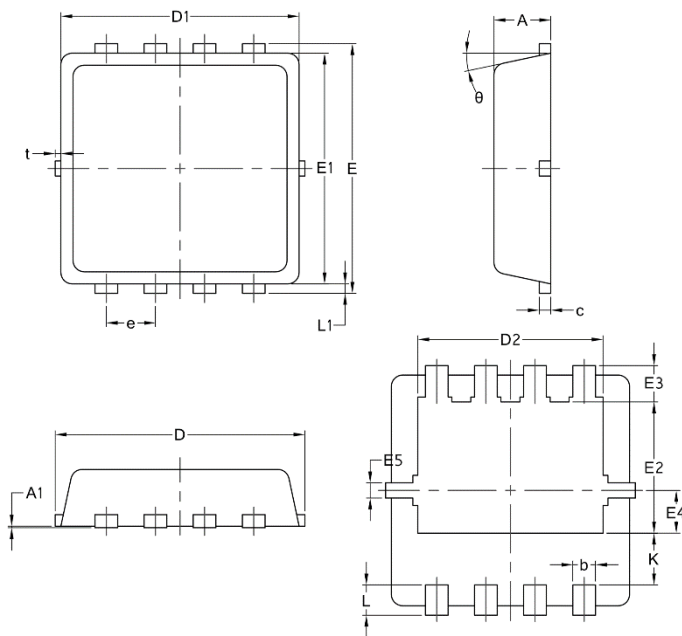
3. Flow (wave) soldering (solder dipping)

Product	Peak Temperature	Dipping Time
Pb devices	245°C ±5°C	5sec ±1sec
Pb-Free devices	260°C +0/-5°C	5sec ±1sec

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- MOS 管电路是静电敏感元器件，且对生产环境要求较严，建议在存放及生产操作时一定要避免静电干扰，经锡炉或回焊炉的温度切勿超过 260 度。

Package Mechanical Data-DFN3*3-8L-JQ Single



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14